

# SPECIFICATIONS

<b>Customer</b>	
<b>Product Name</b>	<b>Multi-layer Chip Ferrite Bead</b>
<b>Sunlord Part Number</b>	<b>UPZ0603U Series</b>
<b>Customer Part Number</b>	

New Released,  Revised]

SPEC No.: **UPZ0502230000**

【This SPEC is total 9 pages.】

【ROHS Compliant Parts】

Approved By	Checked By	Issued By

## Shenzhen Sunlord Electronics Co., Ltd.

Address: Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China 518110  
 Tel: 0086-755-29832660 Fax: 0086-755-82269029 E-Mail: sunlord@sunlordinc.com

**【For Customer approval Only】**

Date: \_\_\_\_\_

Qualification Status:  Full  Restricted  Rejected

Approved By	Verified By	Re-checked By	Checked By

Comments:  
 \_\_\_\_\_

**【Version change history】**

Rev.	Effective Date	Changed Contents	Change Reasons	Approved By
01	/	New release	/	Guo hai

**【Caution】**

All products listed in this specification are developed, designed and intended for use in general electronics equipment. The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require especially high reliability, or whose failure, malfunction or trouble might directly cause damage to society, person, or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below. Please contact us for more details if you intend to use our products in the following applications.

1. Aircraft equipment
2. Aerospace equipment
3. Undersea equipment
4. nuclear control equipment
5. military equipment
6. Power plant equipment
7. Medical equipment
8. Transportation equipment (automobiles, trains, ships,etc.)
9. Traffic signal equipment
10. Disaster prevention / crime prevention equipment
11. Applications of similar complexity or with reliability requirements comparable to the applications listed in the above

1. Scope

This specification applies to UPZ0603U Series of multi-layer ferrite chip bead.

2. Product Description and Identification (Part Number)

- 1) Description:  
UPZ0603U Series of ultra large current chip ferrite bead.
- 2) Product Identification (Part Number)

UPZ 0603 U 330 -1R5 T F  
 ① ② ③ ④ ⑤ ⑥ ⑦

①	Type
UPZ	For Ultra Large Current

②	External Dimensions (L X W)[mm]
0603 [0201]	0.6 X 0.3

③	Material Code
U	

④	Nominal Impedance
Example	Nominal Value
330	33Ω
121	120Ω

⑥	Packing
T	Tape Carrier Package

⑤	Rated Current
R90	0.9A
1R5	1.5A

⑦	HSF Products
Hazardous Substance Free Products	

3. Electrical Characteristics

Please refer to Appendix A (Page 10).

- 1) Operating and storage temperature range (individual chip without packing): -55°C ~ +125°C.
- 2) Storage temperature range (packaging conditions):-10°C~+40°C and RH 70% (Max.)

4. Shape and Dimensions

- 1) Dimensions and recommended PCB pattern for reflow soldering: See Fig.4-1, Fig.4-2 and Table 4-1.
- 2) Structure: See Fig. 4-3 and Fig. 4-4.

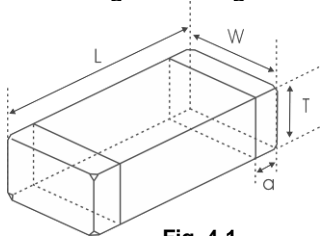


Fig. 4-1

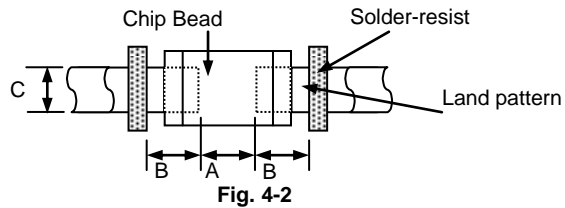


Fig. 4-2

[Table 4-1]

Unit: mm [inch]

Type	L	W	T	a	A	B	C
0603 [0201]	0.6±0.05 [.024±0.002]	0.3±0.05 [.012±.002]	0.3±0.05 [.012±.002]	0.15±0.05 [.006±.002]	0.2~0.3	0.2~0.3	0.3~0.35

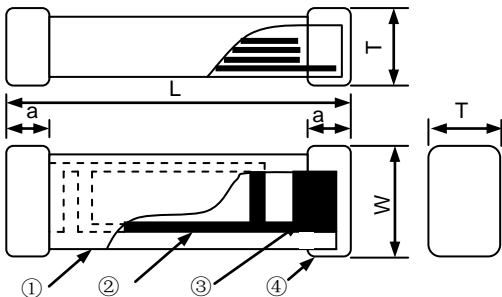


Fig. 4-3

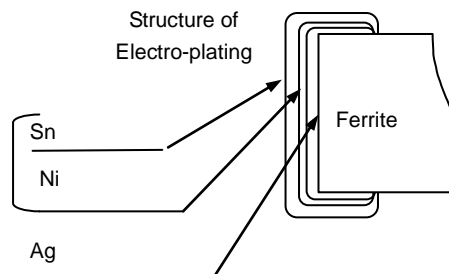


Fig. 4-4

- ① Ferrite for Bead Series
- ② Internal electrode (Ag)
- ③ Pull out electrode(Ag)
- ④-1 Terminal electrode: Inside (Ag)
- ④-2 Outside (Electro-plating Ni-Sn)

3) Material Information: See **Table 4-2**.

[Table 4-2]

Code	Part Name	Material Name
①	Ferrite Body	Ferrite Powder
②	Inner Coils	Silver Paste
③	Pull-out Electrode (Ag)	Silver Paste
④-1	Terminal Electrode: Inside Ag	Termination Silver Composition
④-2	Electro-Plating: Ni/Sn plating	Plating Chemicals

**5. Test and Measurement Procedures**

**5.1 Test Conditions**

5.1.1 Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

- a. Ambient Temperature: 20±15°C
- b. Relative Humidity: 65±20%
- c. Air Pressure: 86kPa to 106kPa

5.1.2 If any doubt on the results, measurements/tests should be made within the following limits:

- a. Ambient Temperature: 20±2°C
- b. Relative Humidity: 65±5%
- c. Air Pressure: 86kPa to 106kPa

**5.2 Visual Examination**

- a. Inspection Equipment: 20x magnifier

**5.3 Electrical Test**

5.3.1 DC Resistance (DCR)

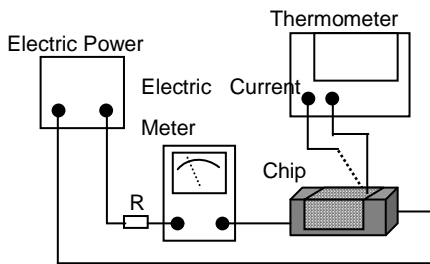
- a. Refer to **Appendix A**.
- b. Test equipment (Analyzer): High Accuracy Milliohmmeter-HP4338B or equivalent.

5.3.2 Impedance (Z)

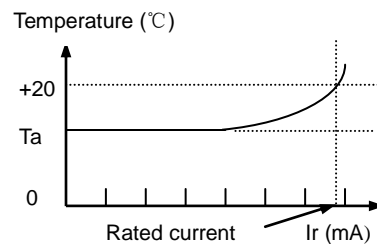
- a. Refer to **Appendix A**.
- b. Test equipment: High Accuracy RF Impedance /Material Analyzer-E4991A or equivalent.  
Test fixture: HP16197A for 0603, HP16192A for 1005/1608/2012/3216.  
Test signal: -20dBm or 50mV
- c. Test frequency refers to **Appendix A**.

5.3.3 Rated Current

- a. Refer to **Appendix A**.
- b. Test equipment (see **Fig.5.3.3-1**): Electric Power, Electric current meter, Thermometer.
- c. Measurement method (see **Fig. 5.3.3-1**):
  1. Set test current to be 0 mA.
  2. Measure initial temperature of chip surface.
  3. Gradually increase voltage and measure chip temperature for corresponding current.
- d. Definition of Rated Current (Ir): Ir is direct electric current as chip surface temperature rose just 20°C against chip initial surface temperature (Ta) (see **Fig. 5.3.3-2**)

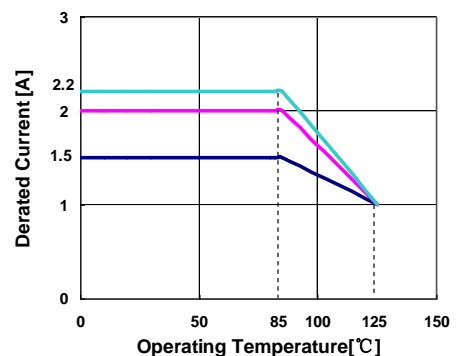


**Fig. 5.3.3-1**

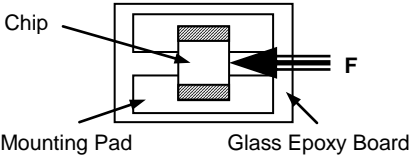
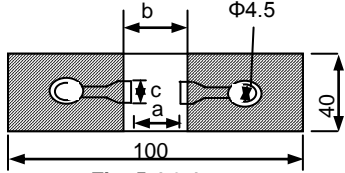
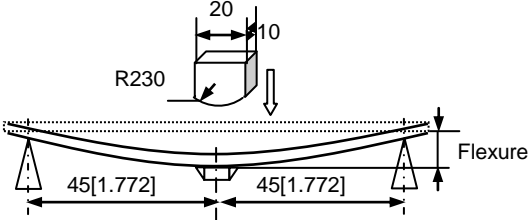
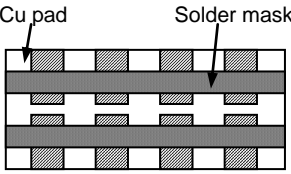


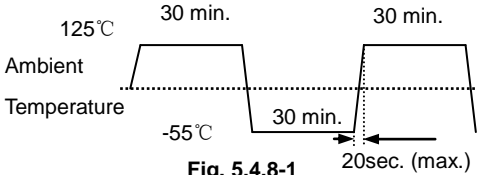
**Fig. 5.3.3-2**

- e. When operating temperatures exceeding +85°C, derating of current is necessary for chip ferrite beads for which rated current is 1000mA over. Please apply the derating curve shown in chart according to the operating temperature.



5.4 Reliability Test

Items	Requirements	Test Methods and Remarks								
5.4.1 Terminal Strength	No removal or split of the termination or other defects shall occur.  Fig.5.4.1-1	① Solder the bead to the testing jig (glass epoxy board shown in Fig. 5.4.1-1) using leadfree solder. Then apply a force in the direction of the arrow. ② 2N force for 0603 series, ③ Keep time: 10±1s. ④ Speed: 1.0mm/s.								
5.4.2 Resistance to Flexure	No visible mechanical damage. Unit: mm [inch] <table border="1" data-bbox="325 562 756 647"> <thead> <tr> <th>Type</th> <th>a</th> <th>b</th> <th>c</th> </tr> </thead> <tbody> <tr> <td>0603[0201]</td> <td>0.25</td> <td>0.8</td> <td>0.3</td> </tr> </tbody> </table>  Fig. 5.4.2-1	Type	a	b	c	0603[0201]	0.25	0.8	0.3	① Solder the bead to the test jig (glass epoxy board shown in Fig. 5.4.2-1) Using a leadfree solder. Then apply a force in the direction shown Fig. 5.4.2-2. ② Flexure: 2mm. ③ Pressurizing Speed: 0.5mm/sec. ④ Keep time: 30 sec.  Fig. 5.4.2-2
Type	a	b	c							
0603[0201]	0.25	0.8	0.3							
5.4.3 Vibration	① No visible mechanical damage. ② Impedance change: within ±20%  Glass Epoxy Board Fig. 5.4.3-1	① Solder the bead to the testing jig (glass epoxy board shown in Fig. 5.4.3-1) using leadfree solder. ② The bead shall be subjected to a simple harmonic motion having total amplitude of 1.5 mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz. ③ The frequency range from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions (total of 6 hours).								
5.4.4 Dropping	① No visible mechanical damage. ② Impedance change: within ±20%.	Drop chip bead 10 times on a concrete floor from a height of 100 cm.								
5.4.5 Temperature	Measured: Impedance No defects.	Temperature range: -55℃ ~ 125℃. Reference temperature: +20℃.								
5.4.6 Solderability	① No visible mechanical damage. ② Wetting shall exceed 75% coverage for 0603 series; exceed 95% for others	① Solder temperature:240±2℃ ② Duration: 3 sec. ③ Solder: Sn/3.0Ag/0.5Cu. ④ Flux: 25% Resin and 75% ethanol in weight.								
5.4.7 Resistance to Soldering Heat	① No visible mechanical damage. ② Wetting shall exceed 75% coverage for 0603 series; exceed 95% for others ③ Impedance change: within ±20%.	① Solder temperature :260±3℃ ② Duration: 5 sec. ③ Solder: Sn/3.0Ag/0.5Cu. ④ Flux: 25% Resin and 75% ethanol in weight. ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.								

<p>5.4.8 Thermal Shock</p>	<p>① No mechanical damage. ② Impedance change: Within <math>\pm 20\%</math>.</p>  <p style="text-align: center;"><b>Fig. 5.4.8-1</b></p>	<p>① Temperature, Time: (See <b>Fig.5.4.8-1</b>) -55°C for 30±3 min→125°C for 30±3min. ② Transforming interval: Max. 20 sec. ③ Tested cycle: 100 cycles. ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</p>
<p>5.4.9 Resistance to Low Temperature</p>	<p>① No mechanical damage. ② Impedance change: within <math>\pm 20\%</math>.</p>	<p>① Temperature: -55±2°C ② Duration: 1000<sup>+24</sup> hours. ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</p>
<p>5.4.10 Resistance to High Temperature</p>	<p>① No mechanical damage. ② Impedance change: within <math>\pm 20\%</math>.</p>	<p>① Temperature: 125±2°C ② Duration: 1000<sup>+24</sup> hours. ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</p>
<p>5.4.11 Damp Heat (Steady States)</p>	<p>① No mechanical damage. ② Impedance change: Within <math>\pm 20\%</math>.</p>	<p>① Temperature: 60±2°C ② Humidity: 90% to 95% RH. ③ Duration: 1000<sup>+24</sup> hours. ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</p>
<p>5.4.12 Loading Under Damp Heat</p>	<p>① No visible mechanical damage. ② Impedance change: within <math>\pm 20\%</math>.</p>	<p>① Temperature: 60±2°C ② Humidity: 90% to 95% RH. ③ Duration: 1000<sup>+24</sup> hours. ④ Applied current: Rated current. ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</p>
<p>5.4.13 Loading at High Temperature (Life Test)</p>	<p>① No visible mechanical damage. ② Impedance change: within <math>\pm 20\%</math>.</p>	<p>① Temperature: 125±2°C ② Duration: 1000<sup>+24</sup> hours. ③ Applied current: Rated current. ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.</p>

**6. Packaging, Storage**

**6.1 Packaging**

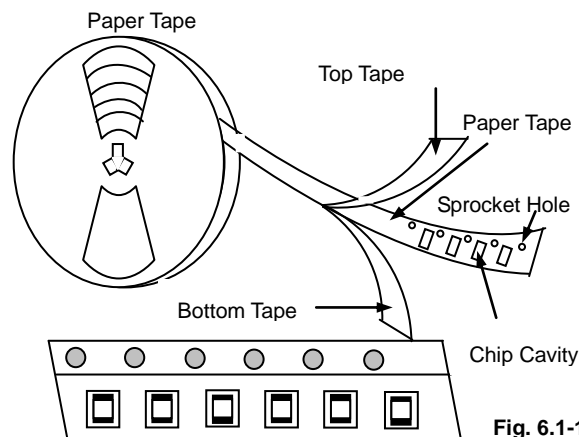
Tape Carrier Packaging:

Packaging code: T

- a. Tape carrier packaging are specified in attached figure **Fig.6.1-1~3**
- b. Tape carrier packaging quantity please see the following table:

Type	0603[0201]
T(mm)	0.3±0.15
Tape	Paper Tape
Quantity	15K

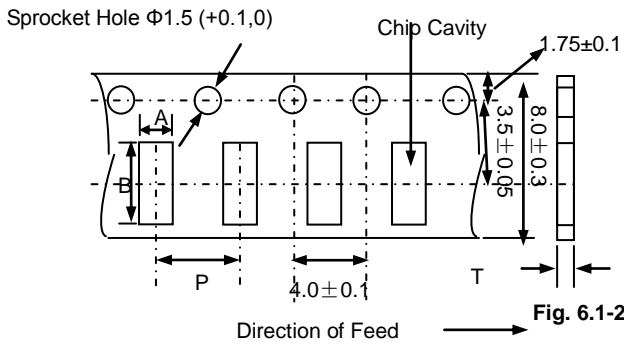
(1) Taping Drawings (Unit: mm)



**Fig. 6.1-1**

**Remark:** The sprocket holes are to the right as the tape is pulled toward the user.

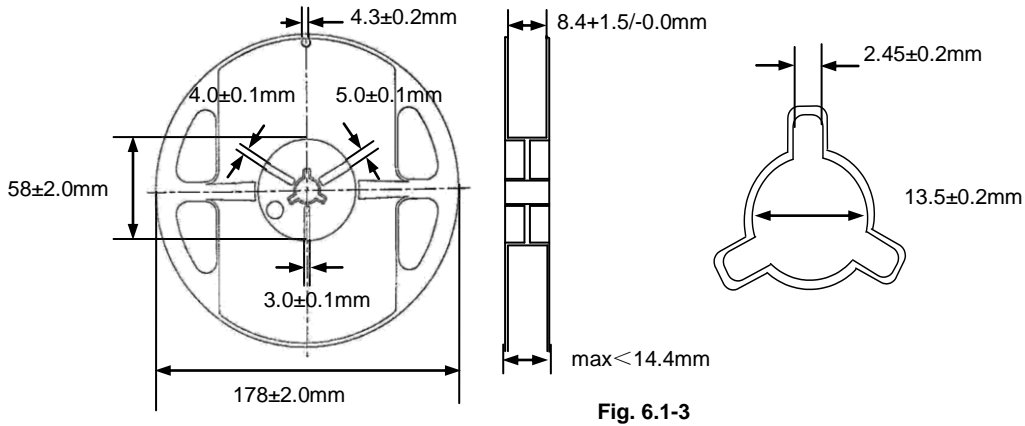
(2) Taping Dimensions (Unit: mm)



Paper Tape

Type	A	B	P	T max
0603[0201]	0.40±0.1	0.70±0.1	2.0±0.1	0.55

3) Reel Dimensions (Unit: mm)



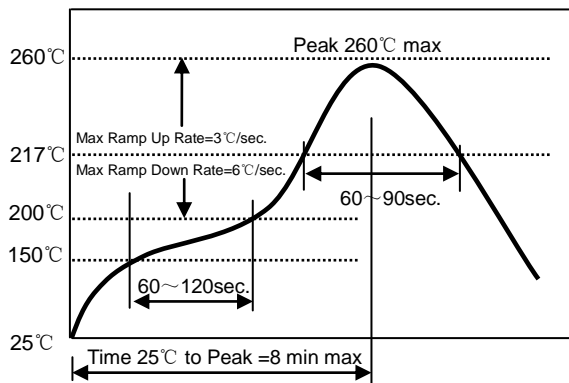
6.2 Storage

- a. The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Package must be stored at 40°C or less and 70% RH or less.
- b. The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust of harmful gas (e.g. HCl, sulfurous gas of H<sub>2</sub>S).
- c. Packaging material may be deformed if package are stored where they are exposed to heat of direct sunlight.
- d. Solderability specified in **Clause 5.4.6** shall be guaranteed for 6 months from the date of delivery on condition that they are stored at the environment specified in **Clause 3**. For those parts, which passed more than 6 months shall be checked solder-ability before use.

7. Recommended Soldering Technologies

7.1 Re-flowing Profile:

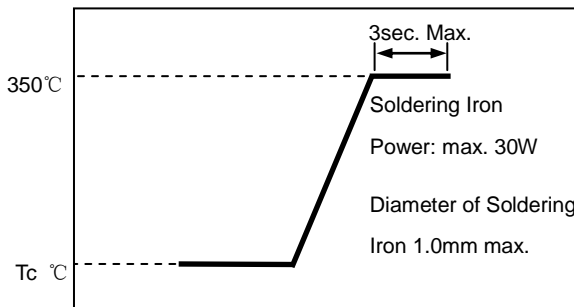
- △ Preheat condition: 150 ~200°C/60~120sec.
- △ Allowed time above 217°C: 60~90sec.
- △ Max temp: 260°C
- △ Max time at max temp: 10sec.
- △ Solder paste: Sn/3.0Ag/0.5Cu
- △ Allowed Reflow time: 2x max



[Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process, and should not exceed the parameters as the Reflow profile shows.]

7.2 Iron Soldering Profile.

- △ Iron soldering power: Max.30W
- △ Pre-heating: 150 °C / 60sec.
- △ Soldering Tip temperature: 350°C Max.
- △ Soldering time: 3sec Max.
- △ Solder paste: Sn/3.0Ag/0.5Cu
- △ Max.1 times for iron soldering



[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]



8.

Appendix A: Electrical Characteristics

I. UPZ0603U Series of Beads

Part Number	Impedance ( $\Omega$ )	Z Test Freq. (MHz)	DCR ( $\Omega$ ) Max.	I <sub>r</sub> (mA) Max.	Thickness (mm) [inch]
UPZ0603U220-1R8TF	22±25%	100	0.04	1800	0.3±0.05 [.012±.002]
UPZ0603U330-1R5TF	33±25%	100	0.055	1500	
UPZ0603U470-1R0TF	47±25%	100	0.12	1000	
UPZ0603U800-1R0TF	80±25%	100	0.13	1000	

Impedance Frequency Characteristics

